

ABSTRACT

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Method of testing wire-bond connections between a bonding wire and a substrate surface, which are produced by a bonding head with a bonding tool and a wire clamp associated with the bonding tool, under pressure and the action of ultrasound

10 and/or heat, wherein after the bonded connection has been created, the bonding head or the bonding tool is raised a short distance away from the bonding site, the bonding wire is firmly gripped by the wire clamp, and the bonding head or the wire clamp with bonding wire gripped therein is raised for a second
15 distance, during which process the tensile force acting on the bonding wire is detected.

(Figure)

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